



## Product End-of-Life Disassembly Instructions

**Product Category:** Workstation

**Marketing Name / Model**  
[List multiple models if applicable.]

HP Z6 G5 Workstation ENERGY STAR

FCLSA-2202A

FCLSA-2202B

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact [HP's Sustainability Contact](#).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	<input checked="" type="checkbox"/> Main board (MB) PCB*1 <input checked="" type="checkbox"/> Solid state drive (SSD) PCB*2 <input type="checkbox"/> Wireless WAN module (WWAN) PCB <input type="checkbox"/> Touch module PCB <input checked="" type="checkbox"/> Power supply PCB*4 <input checked="" type="checkbox"/> External Keyboard (KB)*1 <input checked="" type="checkbox"/> External Mouse*1 <input checked="" type="checkbox"/> Switch Card*1 <input checked="" type="checkbox"/> Memory*4 <input checked="" type="checkbox"/> graphic card PCB*1 <input checked="" type="checkbox"/> HDD PCB*1	16
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	<input checked="" type="checkbox"/> RTC/CMOS battery <input type="checkbox"/> Others: _____	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: <input type="checkbox"/> screws <input type="checkbox"/> snaps <input type="checkbox"/> adhesive <input type="checkbox"/> other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner		0

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Last revalidation date 09-May-2022

HPI instructions for this template are available at [EL-MF877-01](#)

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
lamps, switches, batteries		
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	<input type="checkbox"/> Panel LCD	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	<input checked="" type="checkbox"/> Power Supply capacitor(s) or condenser(s)	2
External electrical cables and cords	<input checked="" type="checkbox"/> AC power cord <input type="checkbox"/> Audio, video or data cables <input type="checkbox"/> Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Hexagon Screw Driver	T-15
Crisscross Screw Driver	PH1
Heatgun	N/A
Suction cup	N/A

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

Figure1 Open and remove the access panel  
Figure2 Remove the P-MID-RETAINER  
Figure3 Disconnect the HDD SATA cable from HDD  
Figure4 Press the latches of the HDD rail to remove the HDD from cage.  
Figure5 Remove the HDD from HDD tray. See below HDD PCB area>10 sq cm.  
Figure6 Press the HDD's latch on HDD tray, and remove the HDD tray from HDD cage  
Figure7 Disconnect the cooler cable  
Figure8 Remove the 2pcs SSD. See below SSD PCB area>10 sq cm.  
Figure9 Loose the PCIE retainer.  
Figure10 Remove the graphic card from MB.  
Figure11 Remove the 4pcs memories from MB  
Figure12 Disconnect the PSU cable from MB  
Figure13 Loose the 4 screws of the PSU.  
Figure14 Press the latch to remove the PSU from chassis.  
Figure15 Disconnect rear system fan cable from MB and remove the fan.  
Figure16 Press the latches to remove the rear system fan.  
Figure17 Press the 4 latches to separate the fan guard from rear system fan.  
Figure18 Press the latch and disconnect the cable from MB.  
Figure19 Separate interlock holder from cable.  
Figure20 Release the PCI snaps.  
Figure21 Disconnect all other cables from MB.  
Figure22 Disconnect the cooler cable from MB.  
Figure23 Press the bottom and loosen the screws of cooler.  
Figure24 Remove the CPU from the cooler  
Figure25 Press the guide and remove the front upper chassis fan and fan guard.  
Figure26 Push the connector and remove it.  
Figure27 Press the 2 latch to Separate the fan from front fan housing.  
Figure28 Loose the screws of the MB and remove the MB from chassis.  
Figure29 Remove the battery from the MB.  
Figure30 Press the button and remove the heat sink.  
Figure31 Press the latch to remove the cover antenna pirate from chassis.  
Figure32 Remove the front panel from chassis.  
Figure33 Release the latch.  
Figure34 Remove the FIO module and ODD devices from cage  
Figure35 Loosen the screws(x2) of speaker and release speaker.  
Figure36 Disconnect the speaker cable from switch card  
Figure37 Release the front panel mount cable from clip  
Figure38 Disconnect the front panel mount cable from switch card  
Figure39 Release the front panel mount cable by push out 2 pins fixed front side in switch card tray.  
Figure40 Release the front panel mount cable by push out 2 pins fixed black side in switch card tray.  
Figure41 Loose the 4pcs switch card PCA screws and remove the switch card PCA.  
Figure42 Remove the SD card reader carrier.  
Figure43 Loosen the left and right side hooks of switch card panel.  
Figure44 Loosen the 2pcs bottom side hooks of switch card panel.  
Figure45 Detailed parts of switch card assembly.  
Figure46 Loose the 2 screws to remove the front handle from chassis.  
Figure47 Use tool to unscrew five screws to loosen top cover. Remove top cover from bottom chassis.  
Figure48 Remove the stand-off & Mylar from PCBA by hand-pulling. Use tool to unscrew three screws to loosen EMI board.  
Figure49 Use tool to remove the cable tie.  
Figure50 Disconnect AC inlet connector and CN602A, CN601B cable connector from PCBA.Remove EMI board.  
Figure51 Identity PCB area > 10 cm<sup>2</sup> for further treatment (EMI board: 161.2053 cm<sup>2</sup>).  
Figure52 Identity PCB area > 10 cm<sup>2</sup> for further treatment (DC-6112 board: 14.72 cm<sup>2</sup>).  
Figure53 Identity electrolyte capacitor > 2.5 cm for further treatment (Length: 5 cm).  
Figure54 Remove the LED cable from CASE by hand-pulling. Disconnect fan connector from PCBA.  
Use tool to unscrew four screws to loosen Main board. Remove Main board.  
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Figure55 Identity PCB area > 10 cm<sup>2</sup> for further treatment (MAIN board: 160.923 cm<sup>2</sup>).  
 Figure56 Identity PCB area > 10 cm<sup>2</sup> for further treatment (DC-6113 board: 25.506 cm<sup>2</sup>).  
 Figure57 Use tool to remove the cable tie. Use tool to unscrew five screws to loosen FAN & AC cable.  
 Remove FAN & Socket. Use tool to remove the LED holder.  
 Figure58 Remove the insulator from CASE by hand-pulling.

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions \(hp.com\)](https://www.hp.com/End-of-Life-Product-Disassembly-Instructions)





<p>Figure1 Open and remove the access panel.</p> 	<p>Figure2 Remove the P-MID-RETAINER.</p> 
<p>Figure3 Disconnect the HDD SATA cable from HDD.</p> 	<p>Figure4 Press the latches of the HDD rail to remove the HDD from cage.</p> 

Figure5 Remove the HDD from HDD tray. See below HDD PCB area >10 sq cm.



Figure6 Press the HDD's latch on HDD tray, and remove the HDD tray from HDD cage



Figure7 Disconnect the cooler cable.



Figure8 Remove the 2pcs SSD. See below SSD PCA area >10 sq cm.



Figure9 Loose the PCIE retainer.



Figure10 Remove the graphic card from MB.



Identity PCBA > 10 cm<sup>2</sup>



Figure11 Remove the 4pcs memories from MB



Identity PCBA > 10 cm<sup>2</sup>

Figure12 Disconnect the PSU cable from MB

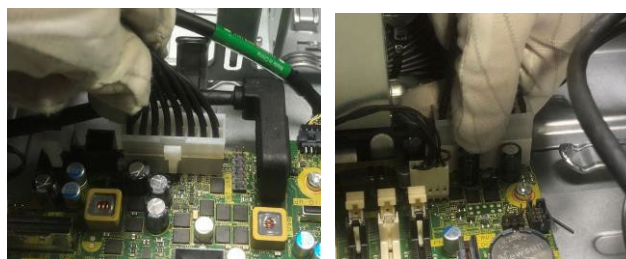


Figure13 Loose the 4 screws of the PSU.

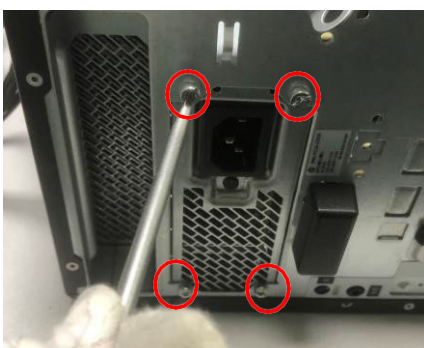


Figure14 Press the latch to remove the PSU from chassis.

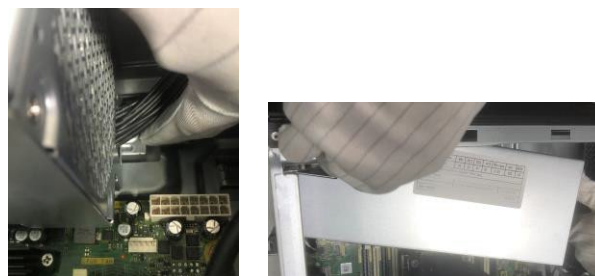


Figure15 Disconnect rear system fan cable from MB and remove the fan.

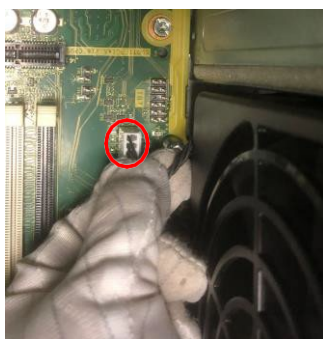


Figure16 Press the latches to remove the rear system fan.

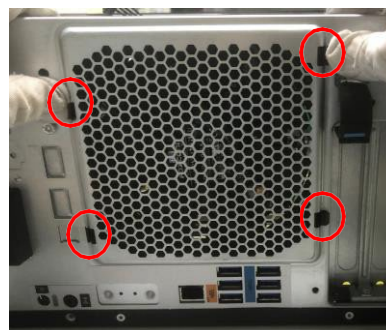


Figure17 Press the 4 latches to separate the fan guard from rear system fan.



Figure18 Press the latch and disconnect the cable from MB.

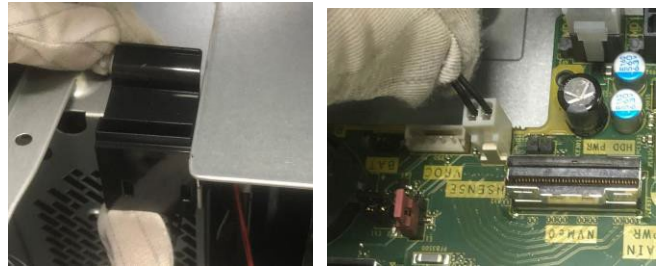


Figure19 Separate interlock holder from cable.



Figure20 Release the PCI snaps.



Figure21 Disconnect all other cables from MB.



Figure22 Disconnect the cooler cable from MB.



Figure23 Press the bottom and loosen the screws of cooler.

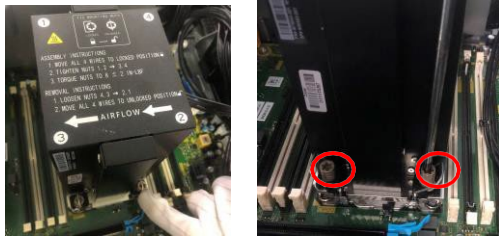


Figure24 Remove the CPU from the cooler

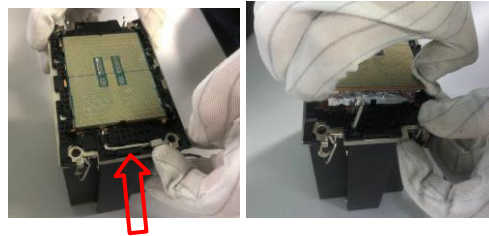


Figure25 Press the guide and remove the front upper chassis fan and fan guard.



Figure26 Push the connector and remove it.

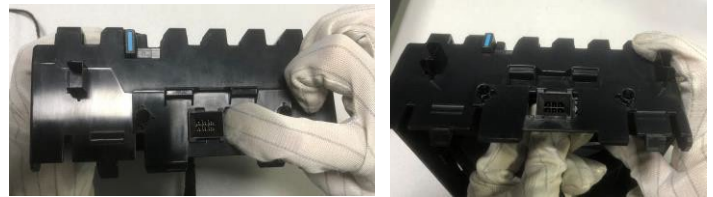


Figure27 Press the 2 latch to Separate the fan from front fan housing.

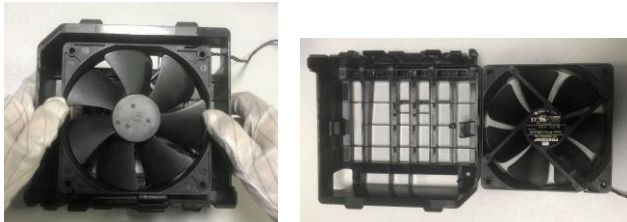
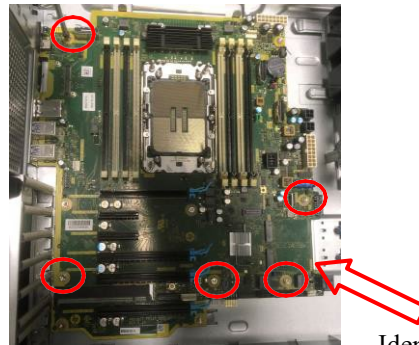


Figure28 Loose the screws of the MB and remove the MB from chassis.



Identity PCBA > 10 cm<sup>2</sup>



Figure29 Remove the battery from the MB.



Figure30 Press th button and remove the heat sink.



Figure31 Press the latch to remove the cover antenna pirate from chassis.

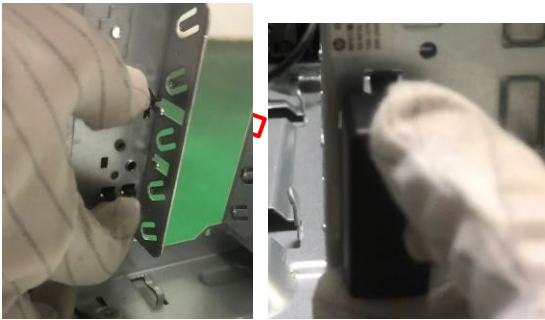


Figure32 Remove the front panel from chassis.



Figure33 Release the latch.



Figure34 Remove the FIO module and ODD devices from cage



Figure35 Loosen the screws(x2) of speaker and release speaker.



Figure36 Disconnect the speaker cable from switch card



Figure37 Release the front panel mount cable from clip



Figure38 Disconnect the front panel mount cable from switch card



Figure39 Release the front panel mount cable by push out 2 pins fixed front side in switch card tray.



Figure40 Release the front panel mount cable by push out 2 pins fixed black side in switch card tray.



Figure41 Loose the 4pcs switch card PCA screws and remove the switch card PCA. See below PCA area>10 sq cm.



PCB area > 10 sq cm

Figure42 Remove the SD card reader carrier.



Figure43 Loosen the left and right side hooks of switch card panel.



Figure44 Loosen the 2pcs bottom side hooks of switch card panel.



Figure45 Detailed parts of switch card assembly.



Figure46 Loose the 2 screws to remove the front handle from chassis.





Figure47 Use tool to unscrew five screws to loosen top cover.Remove top cover from bottom chassis.

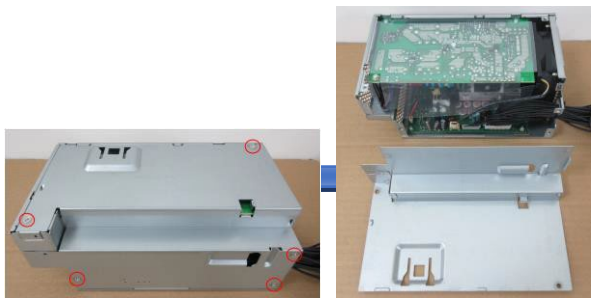


Figure48 Remove the stand-off & Mylar from PCBA by hand-pulling. Use tool to unscrew three screws to loosen EMI board.

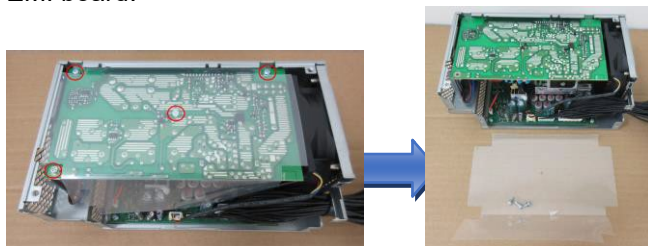


Figure49 Use tool to remove the cable tie.



Figure50 Disconnect AC inlet connector and CN602A, CN601B cable connector from PCBA.Remove EMI board.

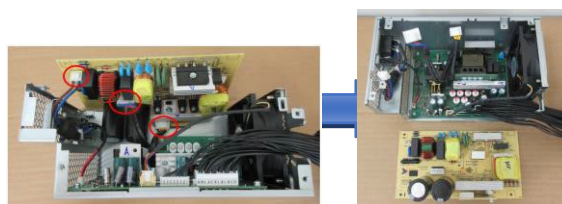


Figure51 Identity PCBA > 10 cm<sup>2</sup> for further treatment (EMI board: 161.2053 cm<sup>2</sup>).

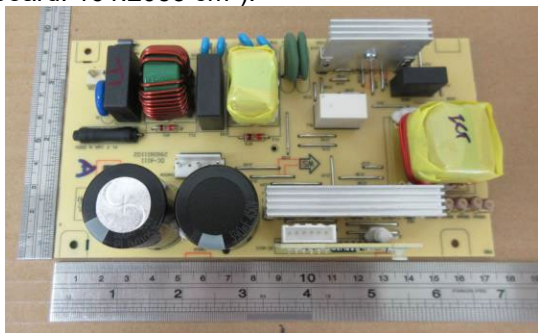


Figure52 Identity PCBA > 10 cm<sup>2</sup> for further treatment (DC-6112 board: 14.72 cm<sup>2</sup>).





Figure53 Identity electrolyte capacitor > 2.5 cm for further treatment (Length: 5 cm).



Figure54 Remove the LED cable from CASE by hand-pulling. Disconnect fan connector from PCBA. Use tool to unscrew four screws to loosen Main board. Remove Main board.

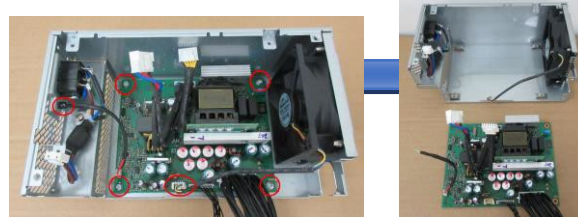


Figure55 Identity PCBA > 10 cm<sup>2</sup> for further treatment (MAIN board: 160.923 cm<sup>2</sup>).

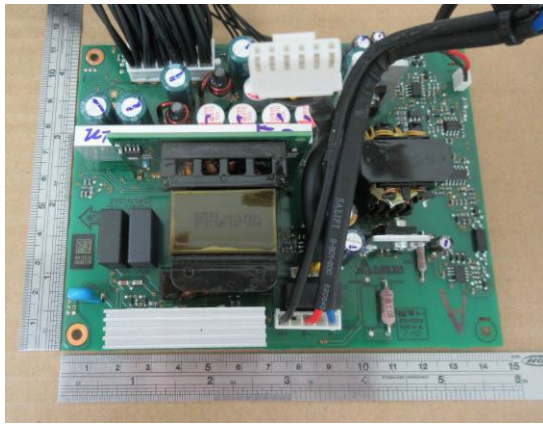


Figure56 Identity PCBA > 10 cm<sup>2</sup> for further treatment (DC-6113 board: 25.506 cm<sup>2</sup>).

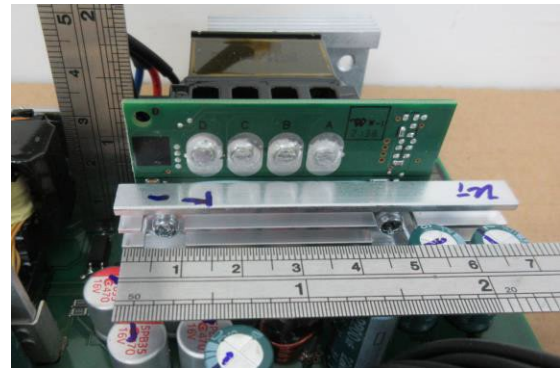


Figure57 Use tool to remove the cable tie. Use tool to unscrew five screws to loosen FAN & AC cable. Remove FAN & Socket. Use tool to remove the LED holder.

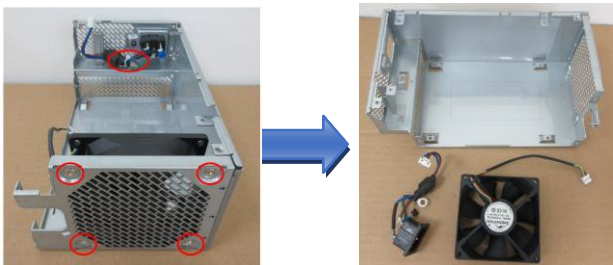


Figure58 Remove the insulator from CASE by hand-pulling.

